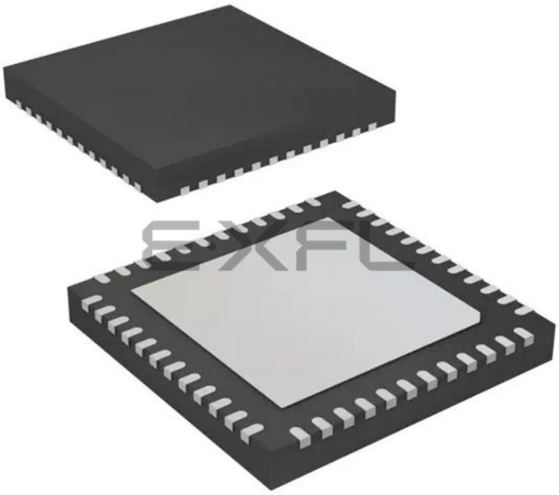
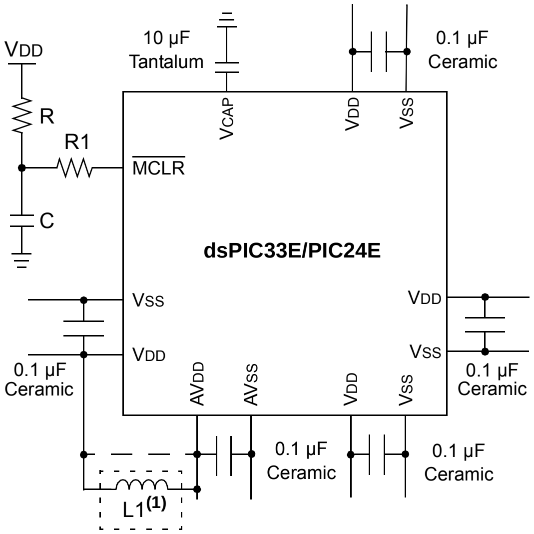
Microchip Technology - PIC24EP512MC204-E/MV Datasheet



Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-UFQFN Exposed Pad
Supplier Device Package	48-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512mc204-e-mv

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$

(i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 1 Ohm) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 30.0 “Electrical Characteristics”** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 27.3 “On-Chip Voltage Regulator”** for details.

2.4 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions:

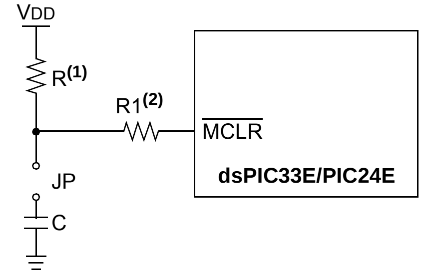
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{\text{MCLR}}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

REGISTER 5-2: NVMADRH: NONVOLATILE MEMORY ADDRESS REGISTER HIGH

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMADR<23:16>:** Nonvolatile Memory Write Address High bits

Selects the upper 8 bits of the location to program or erase in program Flash memory. This register may be read or written by the user application.

REGISTER 5-3: NVMADRL: NONVOLATILE MEMORY ADDRESS REGISTER LOW

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
NVMADR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **NVMADR<15:0>:** Nonvolatile Memory Write Address Low bits

Selects the lower 16 bits of the location to program or erase in program Flash memory. This register may be read or written by the user application.

REGISTER 5-4: NVMKEY: NONVOLATILE MEMORY KEY

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** Key Register (write-only) bits

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Notes
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	`xx`	`111`	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	`xx`	`110`	**1**
Low-Power RC Oscillator (LPRC)	Internal	`xx`	`101`	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	`10`	`011`	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	`01`	`011`	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	`00`	`011`	**1**
Primary Oscillator (HS)	Primary	`10`	`010`	
Primary Oscillator (XT)	Primary	`01`	`010`	
Primary Oscillator (EC)	Primary	`00`	`010`	**1**
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)	Internal	`xx`	`001`	**1**
Fast RC Oscillator (FRC)	Internal	`xx`	`000`	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

9.2 Oscillator Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

9.2.1 KEY RESOURCES

- **“Oscillator”** (DS70580) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

NOTES:

15.1 Output Compare Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

15.1.1 KEY RESOURCES

- **"Output Compare"** (DS70358) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER[2]

R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PENH	PENL	POLH	POLL	PMOD1[1]	PMOD0[1]	OVRENH	OVRENL
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PENH:** PWMxH Output Pin Ownership bit
`1` = PWMx module controls PWMxH pin
`0` = GPIO module controls PWMxH pin

bit 14 **PENL:** PWMxL Output Pin Ownership bit
`1` = PWMx module controls PWMxL pin
`0` = GPIO module controls PWMxL pin

bit 13 **POLH:** PWMxH Output Pin Polarity bit
`1` = PWMxH pin is active-low
`0` = PWMxH pin is active-high

bit 12 **POLL:** PWMxL Output Pin Polarity bit
`1` = PWMxL pin is active-low
`0` = PWMxL pin is active-high

bit 11-10 **PMOD<1:0>:** PWMx # I/O Pin Mode bits[1]
`11` = Reserved; do not use
`10` = PWMx I/O pin pair is in the Push-Pull Output mode
`01` = PWMx I/O pin pair is in the Redundant Output mode
`00` = PWMx I/O pin pair is in the Complementary Output mode

bit 9 **OVRENH:** Override Enable for PWMxH Pin bit
`1` = OVRDAT<1> controls output on PWMxH pin
`0` = PWMx generator controls PWMxH pin

bit 8 **OVRENL:** Override Enable for PWMxL Pin bit
`1` = OVRDAT<0> controls output on PWMxL pin
`0` = PWMx generator controls PWMxL pin

bit 7-6 **OVRDAT<1:0>:** Data for PWMxH, PWMxL Pins if Override is Enabled bits
If OVERENH = `1`, PWMxH is driven to the state specified by OVRDAT<1>.
If OVERENL = `1`, PWMxL is driven to the state specified by OVRDAT<0>.

bit 5-4 **FLTDAT<1:0>:** Data for PWMxH and PWMxL Pins if FLTMOD is Enabled bits
If Fault is active, PWMxH is driven to the state specified by FLTDAT<1>.
If Fault is active, PWMxL is driven to the state specified by FLTDAT<0>.

bit 3-2 **CLDAT<1:0>:** Data for PWMxH and PWMxL Pins if CLMOD is Enabled bits
If current-limit is active, PWMxH is driven to the state specified by CLDAT<1>.
If current-limit is active, PWMxL is driven to the state specified by CLDAT<0>.

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = `1`).
2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a ‘`1`’, the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 17-4: POS1CNTH: POSITION COUNTER 1 HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSCNT<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSCNT<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**POSCNT<31:16>:** High Word Used to Form 32-Bit Position Counter Register (POS1CNT) bits

REGISTER 17-5: POS1CNTL: POSITION COUNTER 1 LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSCNT<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**POSCNT<15:0>:** Low Word Used to Form 32-Bit Position Counter Register (POS1CNT) bits

REGISTER 17-6: POS1HLD: POSITION COUNTER 1 HOLD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSHLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
POSHLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**POSHLD<15:0>:** Hold Register for Reading and Writing POS1CNTH bits

REGISTER 17-13: QEI1LECH: QEI1 LESS THAN OR EQUAL COMPARE HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **QEILEC<31:16>:** High Word Used to Form 32-Bit Less Than or Equal Compare Register (QEI1LEC) bits

REGISTER 17-14: QEI1LECL: QEI1 LESS THAN OR EQUAL COMPARE LOW WORD REGISTER

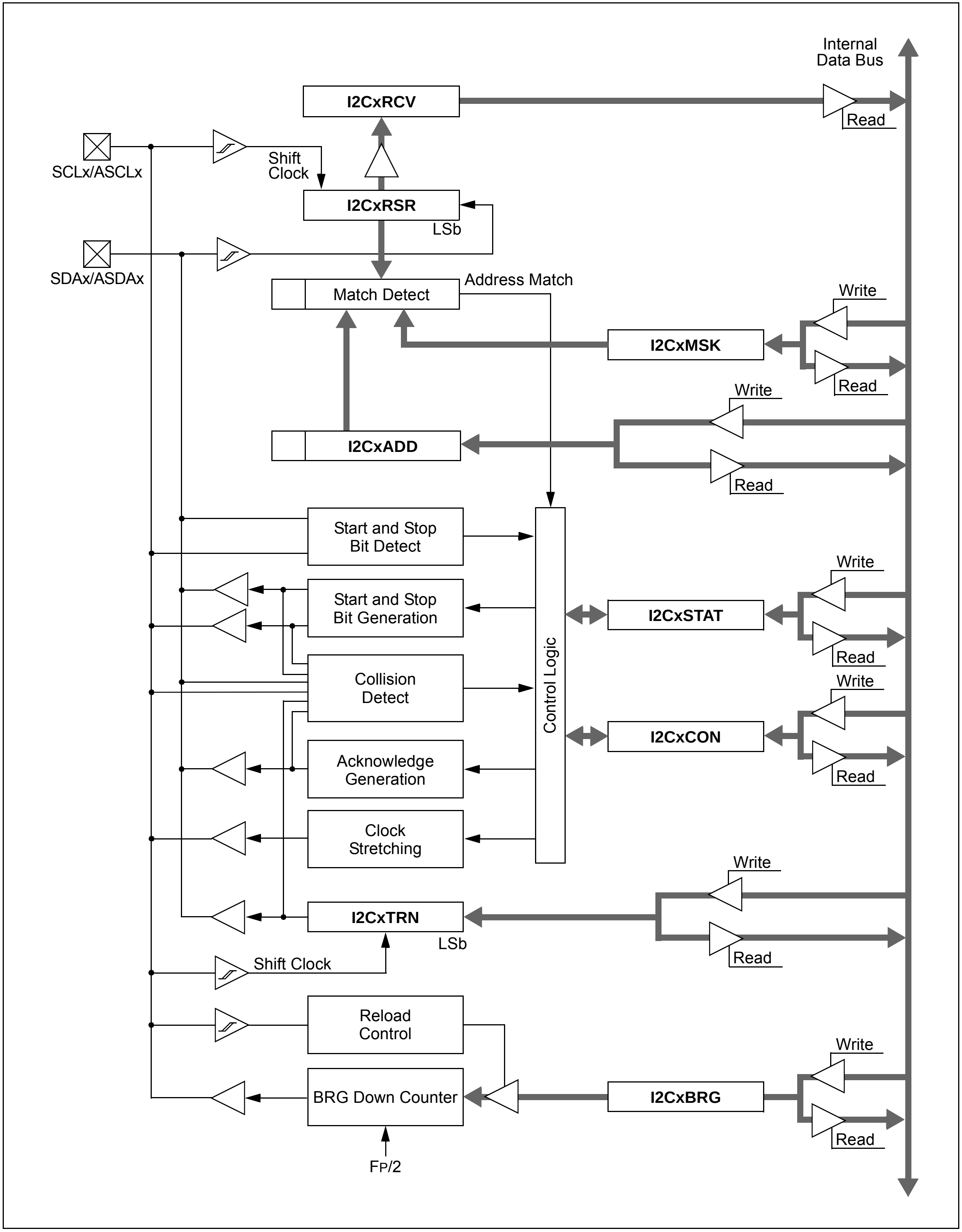
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **QEILEC<15:0>:** Low Word Used to Form 32-Bit Less Than or Equal Compare Register (QEI1LEC) bits

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1 OR 2)



REGISTER 20-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5	**ADDEN:** Address Character Detect bit (bit 8 of received data = `1`) `1` = Address Detect mode is enabled; if 9-bit mode is not selected, this does not take effect `0` = Address Detect mode is disabled
bit 4	**RIDLE:** Receiver Idle bit (read-only) `1` = Receiver is Idle `0` = Receiver is active
bit 3	**PERR:** Parity Error Status bit (read-only) `1` = Parity error has been detected for the current character (character at the top of the receive FIFO) `0` = Parity error has not been detected
bit 2	**FERR:** Framing Error Status bit (read-only) `1` = Framing error has been detected for the current character (character at the top of the receive FIFO) `0` = Framing error has not been detected
bit 1	**OERR:** Receive Buffer Overrun Error Status bit (clear/read-only) `1` = Receive buffer has overflowed `0` = Receive buffer has not overflowed; clearing a previously set OERR bit (`1` → `0` transition) resets the receiver buffer and the UxRSR to the empty state
bit 0	**URXDA:** UARTx Receive Buffer Data Available bit (read-only) `1` = Receive buffer has data, at least one more character can be read `0` = Receive buffer is empty

Note 1: Refer to the **"UART"** (DS70582) section in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UARTx module for transmit operation.

REGISTER 21-16: CxRXFnSID: ECANx ACCEPTANCE FILTER n STANDARD IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	EXIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5	**SID<10:0>:** Standard Identifier bits `1` = Message address bit, SIDx, must be ‘`1`’ to match filter `0` = Message address bit, SIDx, must be ‘`0`’ to match filter
bit 4	**Unimplemented:** Read as ‘`0`’
bit 3	**EXIDE:** Extended Identifier Enable bit If MIDE = `1`: `1` = Matches only messages with Extended Identifier addresses `0` = Matches only messages with Standard Identifier addresses If MIDE = `0`: Ignores EXIDE bit.
bit 2	**Unimplemented:** Read as ‘`0`’
bit 1-0	**EID<17:16>:** Extended Identifier bits `1` = Message address bit, EIDx, must be ‘`1`’ to match filter `0` = Message address bit, EIDx, must be ‘`0`’ to match filter

27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '`1111 1111 1111 1111`'. This makes them appear to be `NOP` instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '`1`'s to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current**(1,2)					
DI50		I/O Pins 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

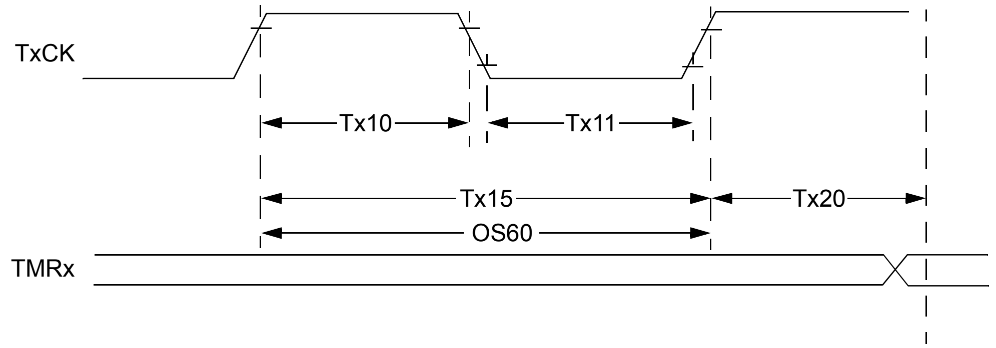
5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-5: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS[1]

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[2]**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescaler value (1, 8, 64, 256)
			Asynchronous	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting bit, TCS (T1CON<1>))		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 30-38: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of F_P or 11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS2}}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS2}}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SS2}}$ ↑ after SCK2 Edge	1.5 T_{CY} + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO2 Data Output Valid after $\overline{\text{SS2}}$ Edge	—	—	50	ns	

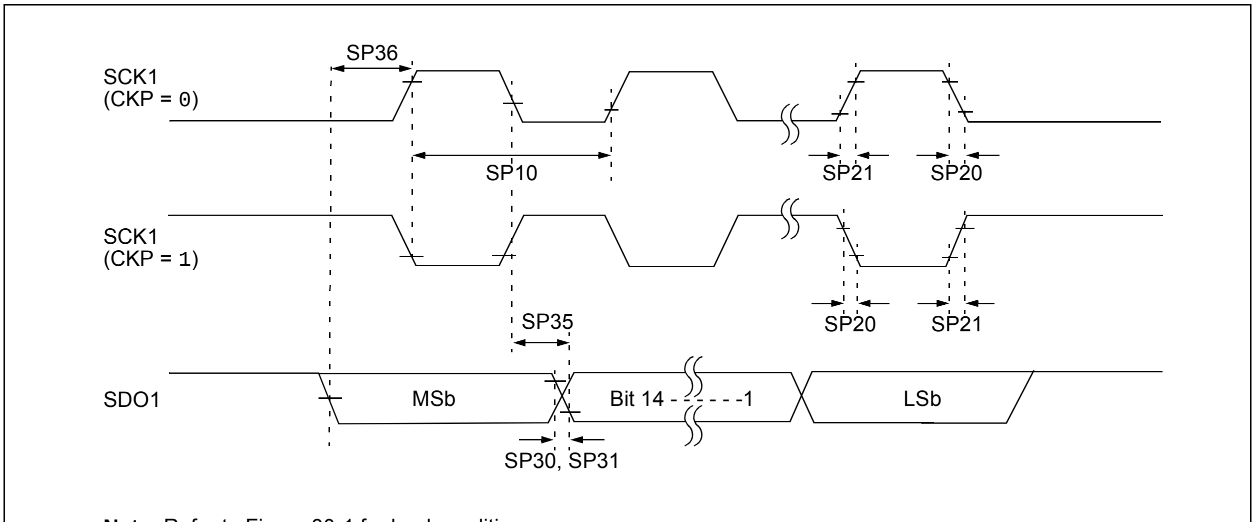
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-23: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-42: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

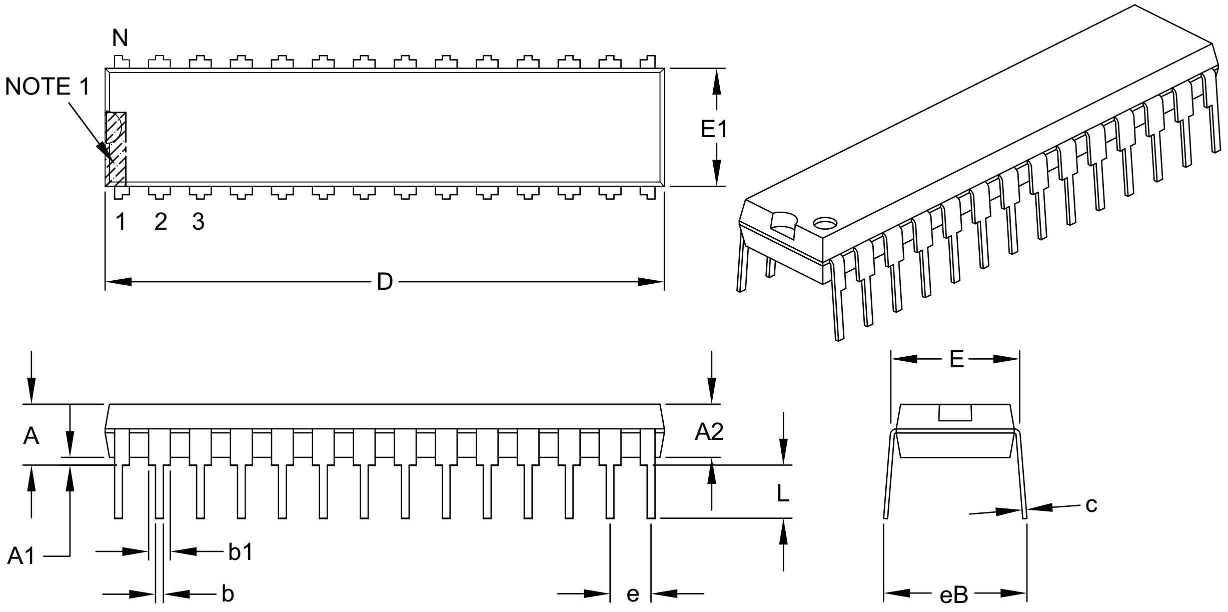
3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

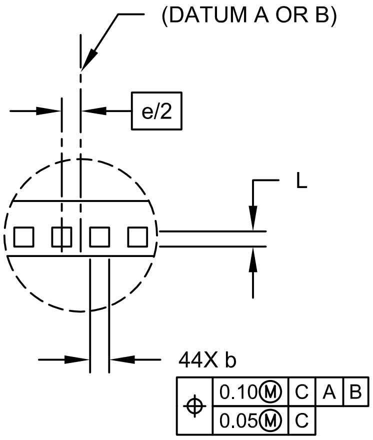
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

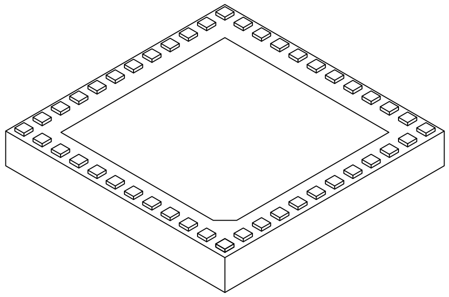
Microchip Technology Drawing C04-070B

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

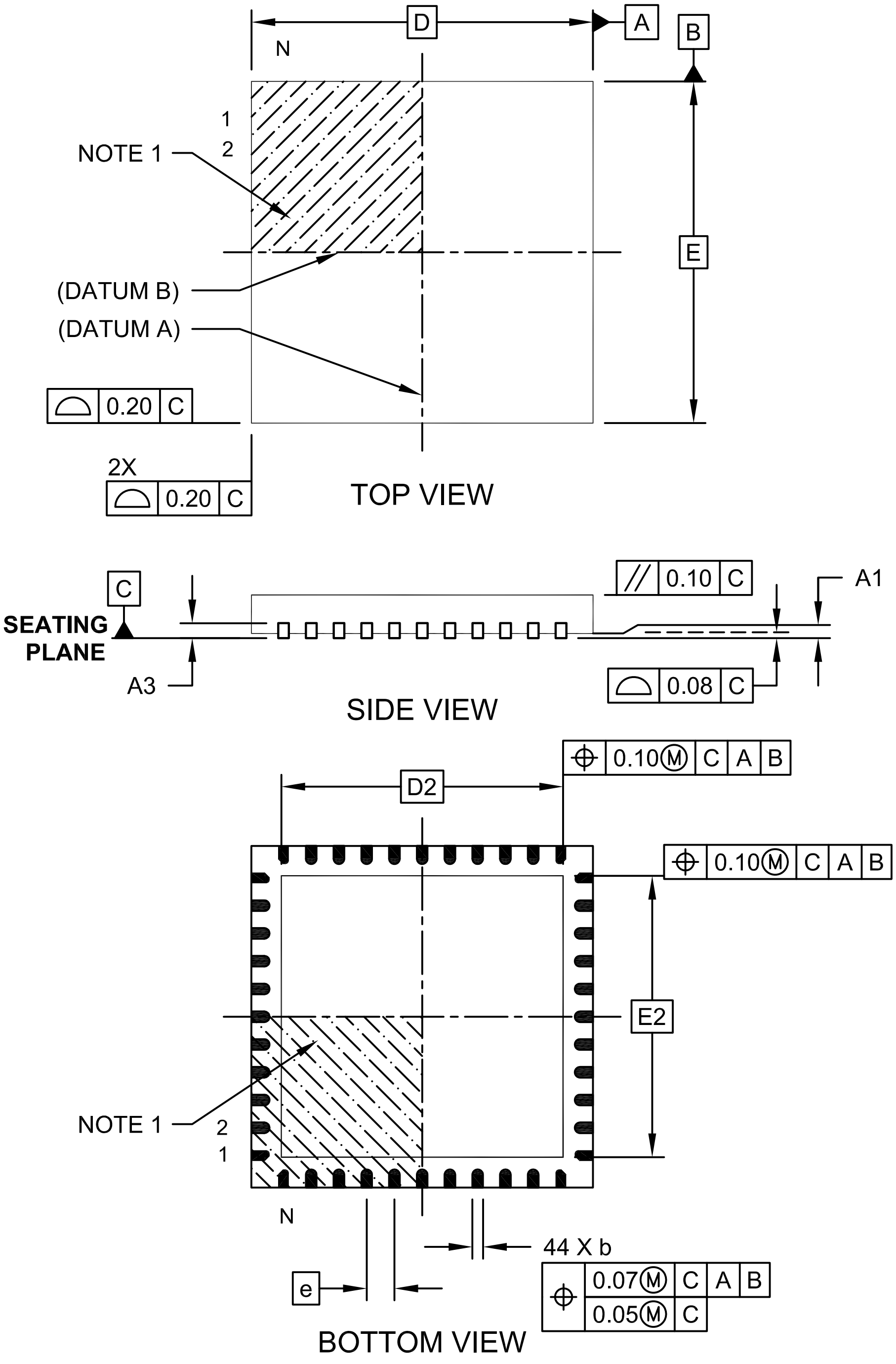
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-103C Sheet 1 of 2

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 16.0 “High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)”	Updated the High-Speed PWM Module Register Interconnection Diagram (see Figure 16-2). Added the TRGCONx and TRIGx registers (see Register 16-12 and Register 16-14, respectively).
Section 21.0 “Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)”	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 22.0 “Charge Time Measurement Unit (CTMU)”	Updated the IRNG<1:0> bit value definitions and added Note 2 in the CTMU Current Control Register (see Register 22-3).
Section 25.0 “Op amp/ Comparator Module”	Updated the Op amp/Comparator I/O Operating Modes Diagram (see Figure 25-1). Updated the User-programmable Blanking Function Block Diagram (see Figure 25-3). Updated the Digital Filter Interconnect Block Diagram (see Figure 25-4). Added **Section 25.1 “Op amp Application Considerations”**. Added Note 2 to the Comparator Control Register (see Register 25-2). Updated the bit definitions in the Comparator Mask Gating Control Register (see Register 25-5).
Section 27.0 “Special Features”	Updated the FICD Configuration Register, updated Note 1, and added Note 3 in the Configuration Byte Register Map (see Table 27-1). Added **Section 27.2 “User ID Words”**.
Section 30.0 “Electrical Characteristics”	Updated the following Absolute Maximum Ratings: • Maximum current out of VSS pin • Maximum current into VDD pin Added Note 1 to the Operating MIPS vs. Voltage (see Table 30-1). Updated all Idle Current (IIDLE) Typical and Maximum DC Characteristics values (see Table 30-7). Updated all Doze Current (IDOZE) Typical and Maximum DC Characteristics values (see Table 30-9). Added Note 2, removed Parameter CM24, updated the Typical values Parameters CM10, CM20, CM21, CM32, CM41, CM44, and CM45, and updated the Minimum values for CM40 and CM41, and the Maximum value for CM40 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Updated Note 2 and the Typical value for Parameter VR310 in the Op amp/ Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Note 1, removed Parameter VRD312, and added Parameter VRD314 to the Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated the Minimum, Typical, and Maximum values for Internal LPRC Accuracy (see Table 30-22). Updated the Minimum, Typical, and Maximum values for Parameter SY37 in the Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Timing Requirements (see Table 30-24). The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-35)